

MSOP-10 Power Dissipation

Power dissipation data for the MSOP-10 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mm×40mm (1600mm² in one side)

1st Inner Metal Layer about 50% tied to the pin 10

2nd Inner Metal Layer does not exist

3rd Inner Metal Layer does not exist

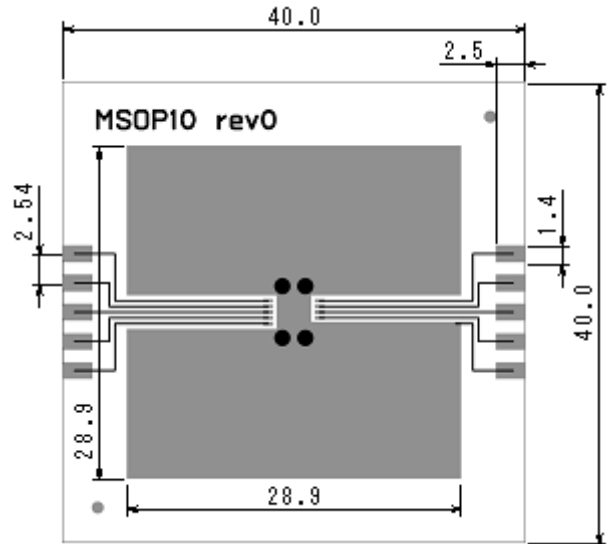
4th Inner Metal Layer about 50% tied to the pin 10

Each pin is tied to the copper traces

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : 10 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	200	

